Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Littelfuse
Expertise Applied | Answers Delivered

SM712 Series 600W Asymmetrical TVS Diode Array

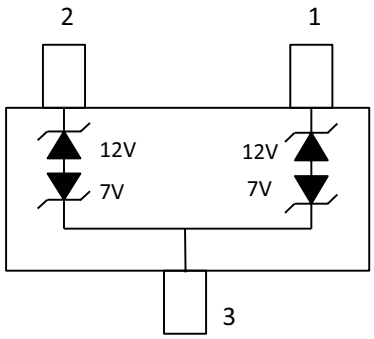
AUTOMOTIVE GRADE | RoHS | Pb GREEN

Description

The SM712 TVS Diode Array is designed to protect RS-485 applications with asymmetrical working voltages (-7V to 12V) from damage due to electrostatic discharge (ESD), electrical fast transients (EFT), and lightning induced surges.

The SM712 can absorb repetitive ESD strikes above the maximum level specified in the IEC 61000-4-2 international standard without performance degradation and safely dissipate up to 19A of 8/20us induced surge current (IEC-61000-4-5 2nd edition) with very low clamping voltages.

Pinout and Functional Block Diagram



Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

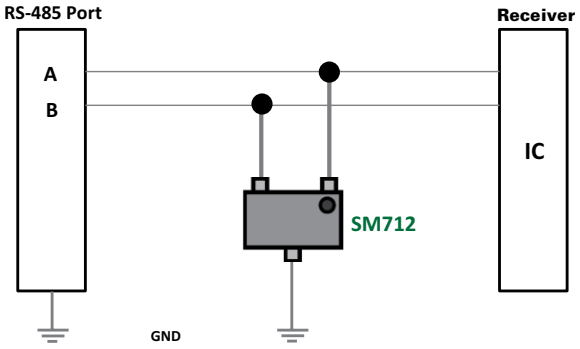
Features

- RoHS compliant and lead-free
- ESD, IEC 61000-4-2, ±30kV contact, ±30kV air
- EFT, IEC 61000-4-4, 50A (5/50ns)
- Lightning, IEC 61000-4-5 2nd edition, 19A (t_P=8/20μs)
- Working Voltages: -7V to 12V
- Low clamping voltage
- Low leakage current
- AEC-Q101 Qualified

Applications

- RS-485
- Fieldbus
- Modbus
- Profibus
- DMX512
- Security Systems
- AutomatedTeller Machines (ATMs)
- Lighting Control - DALI
- Communication Equipments

RS-485 Application Example



Additional Information

Datasheet | Resources | Samples

Revised: 12/12/16

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
P_{Pk}	Peak Pulse Power (t_p=8/20µs)	600	W
I_{PP}	Peak Pulse Current (t_p=8/20µs)	19	A
T_{OP}	Operating Temperature	-40 to 125	°C
T_{STOR}	Storage Temperature	-55 to 150	°C

Notes:

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

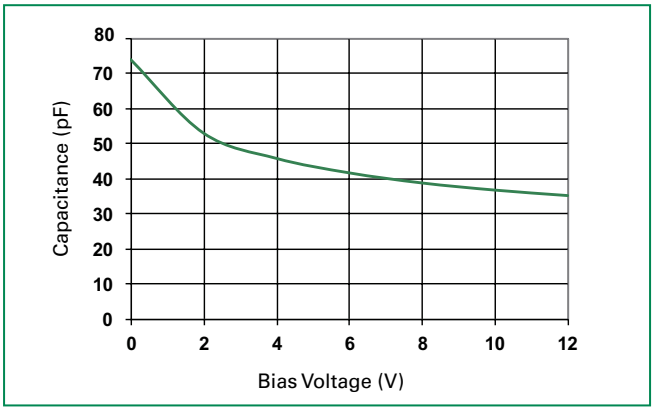
Parameter	Rating	Units
Storage Temperature Range	-55 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

SM712 Electrical Characteristics (T_{OP}=25°C)

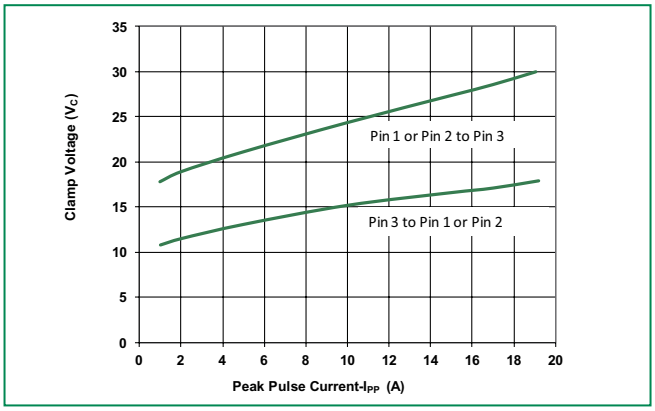
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}	I_R≤1µA, Pin3 to Pin1 or Pin2			7.0	V
		I_R≤1µA, Pin1 or Pin2 to Pin3			12.0	V
Reverse Breakdown Voltage	V_R	I_R=1mA, Pin3 to Pin1 or Pin2	7.5			V
		I_R=1mA, Pin1 or Pin2 to Pin3	13.3			V
Leakage Current	I_{LEAK}	V_R=7V			20	µA
		V_R=12V			1	µA
Clamp Voltage[1]	V_C	I_{PP}=1A, t_p=8/20µs, Pin 1 or Pin 2 to Pin 3			19	V
		I_{PP}=1A, t_p=8/20µs, Pin 3 to Pin 1 or Pin 2			11	V
		I_{PP}=19A, t_p=8/20µs, Pin 1 or Pin 2 to Pin 3			31	V
		I_{PP}=19A, t_p=8/20µs, Pin 3 to Pin 1 or Pin 2			19	V
Dynamic Resistance[1]	R_{DYN}	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		0.5		Ω
ESD Withstand Voltage[1]	V_{ESD}	IEC 61000-4-2 (Contact Discharge)	±30			kV
		IEC 61000-4-2 (Air Discharge)	±30			kV
Diode Capacitance[1]	$C_{I/O-GND}$	Reverse Bias=0V, f=1MHz; Pin 1 or Pin2 to Pin 3			75	pF

Notes : 1. Parameter is guaranteed by design and/or device characterization.

Capacitance vs. Reverse Bias

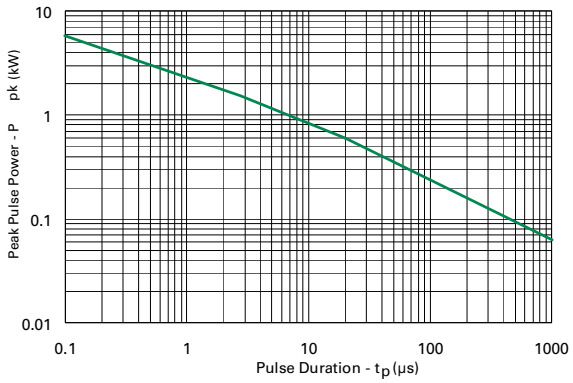


Clamping Voltage vs. I_{PP}

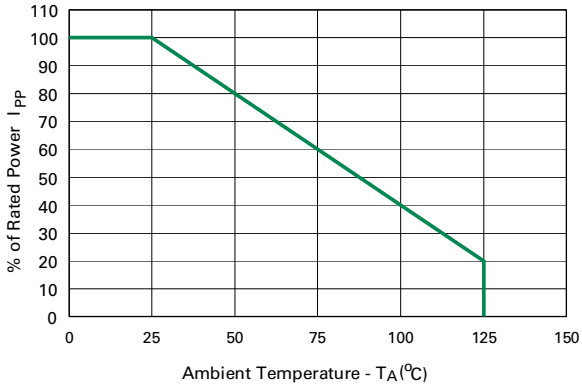


Revised: 12/12/16

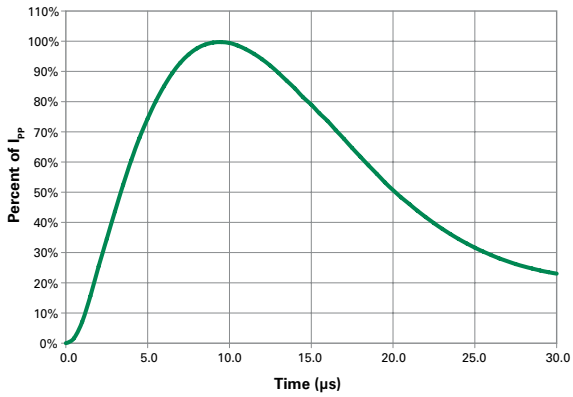
Non-Repetitive Peak Pulse Power vs. Pulse Time



Power Derating Curve



Pulse Waveform



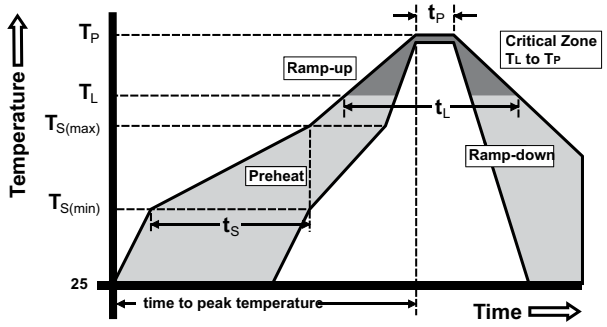
Product Characteristics

Lead Plating	PPF
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substrate material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

Notes :
1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.

Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		$260^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		260°C

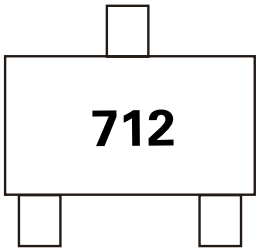


Revised: 12/12/16

TVS Diode Arrays (SPA® Diodes)

General Purpose ESD Protection - SM712

Part Marking System



Part Numbering System

SM 712 - 02 H T G

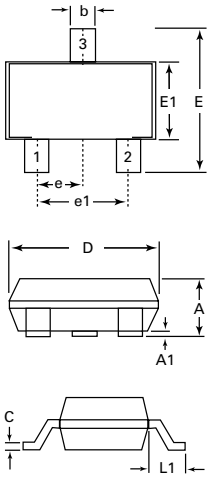
- SM: TVS Diode Arrays (SPA® Diodes)
- 712: Series
- 02: Working Voltage
- H: Package, H: SOT23-3
- T: T= Tape & Reel
- G: G= Green

Number of Channels

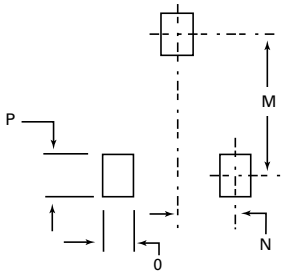
Ordering Information

Part Number	Package	Marking	Min. Order Qty.
SM712-02HTG	SOT23-3	712	3000

Package Dimensions — SOT23-3



Recommended Pad Layout



Package	SOT23-3			
Pins	3			
JEDEC	TO-236			
	Millimeters		Inches	
	Min	Max	Min	Max
A	0.89	1.12	0.035	0.044
A1	0.01	0.1	0.0004	0.004
b	0.3	0.5	0.012	0.020
c	0.08	0.2	0.003	0.008
D	2.8	3.04	0.110	0.120
E	2.1	2.64	0.083	0.104
E1	1.2	1.4	0.047	0.055
e	0.95 BSC		0.038 BSC	
e1	1.90 BSC		0.075 BSC	
L1	0.54 REF		0.021 REF	
M		2.29		.090
N		0.95		0.038
O		0.78		.030TYP
P		0.78		.030TYP

Revised: 12/12/16